AMENDMENTS TO THE CLAIMS:

All pending claims are set forth below. Cancelled and withdrawn claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough.~~ The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), and (not entered). Please AMEND claims 1, 15, and 16 and CANCEL claim 2 without prejudice or disclaimer in accordance with the following:

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1. (currently amended) A plasma display panel comprising:

electrodes arranged on a substrate on a rear side;

a dielectric layer provided to cover the electrodes; and a fluorescent layer formed on a front side of the dielectric layer,

wherein the dielectric layer is formed of a mixture of a base material and a filler having a smaller relative dielectric constant than the base material, and the dielectric layer has a smaller relative dielectric constant ≤ 10 and a larger reflectance than a layer formed of the base material but not containing the filler.

2. (cancelled)

3. (previously presented) A plasma display panel according to claim 1, wherein the filler is a silica powder.

4. (previously presented) A plasma display panel according to claim 1, wherein the filler is an alumina powder.

5. (previously presented) A plasma display panel according to claim 1, wherein the filler is hollow glass micro-balloons.

6. (previously presented) A plasma display panel according to any one of claim 1, wherein the thickness of the dielectric layer is 10 μm or less.

7. (currently amended) A plasma display panel comprising a dielectric layer

in which a filler for enhancing reflectance is dispersed,

wherein the filler comprises pieces individually having outward appearance of flakes whose front and back faces are oriented in a direction along a surface of the dielectric layer, and the dielectric layer has a dielectric constant ≤ 10.

8. (original) A plasma display panel according to claim 7, wherein the filler is mica coated with titanium dioxide.

9. (original) A plasma display panel according to claim 8, wherein the dielectric layer contains a low-melting-point glass as a base material.

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10. (original) A plasma display panel according to claim 9, wherein the content of the filler in the dielectric layer is a value within the range of 10 to 80 wt%.

11. (original) A plasma display panel according to claim 8, wherein the dielectric layer contains silicon oxide as a base material.

12. (original) A plasma display panel according to claim 11, wherein the content of the filler in the dielectric layer is a value within the range of 10 to 80 wt%.

13. (previously presented) A plasma display panel according to claim 7 further comprising barrier ribs for partitioning a discharge space, wherein sidewalls of the barrier ribs are covered with the dielectric layer.

14. (original) A plasma display panel according to claim 13, wherein the barrier ribs are black.

15. (currently amended) A plasma display panel according to claim 14, wherein the black barrier ribs ~~has~~ have a ~~transmissivity~~ transmission per unit length of 10 %/ 10 μm or less to visible light.

16. (currently amended) A plasma display panel according to claim 14,

wherein the dielectric layer has a reflectance per unit length of 50 % / 10 μm or more.

17. (original) A substrate structure to be used for fabrication of a plasma display panel as set forth in claim 13, which is provided with the barrier ribs and the dielectric layer.

18. (original) A substrate structure according to claim 17, wherein the barrier ribs are black.

19. (previously presented) A plasma display panel according to claim 7, wherein a light-shielding layer is provided on a front side with respect to a discharge space and the dielectric layer is provided on a rear side with respect to the light-shielding layer.

20. (original) A substrate structure to be used for fabrication of a plasma display panel as set forth in claim 19, wherein the light-shielding layer and the dielectric layer are provided on a substrate.

21. (withdrawn) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17, the dielectric layer is formed by applying onto a substrate a low-melting-point glass paste in which a flake-form filler for enhancing reflectance is mixed, followed by burning.

22. (withdrawn) A process for manufacturing a substrate structure according to claim 21, wherein the dielectric layer is formed by applying onto a supporting face a low-melting-point glass paste in which flake-form mica coated with titanium dioxide and particulate titanium dioxide are mixed, followed by burning.

23. (withdrawn) A process for manufacturing a substrate structure according to claim 22, wherein the mixture ratio of the particulate titanium oxide to the flake-form mica is a value within the range of 5 to 30 wt%.

24. (withdrawn) A process for manufacturing a substrate structure

according to claim 23, wherein the particulate titanium dioxide has a particle diameter of 5 μm or less.

25. (withdrawn) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17, the dielectric layer is formed by applying onto a substrate a colloidal silica in which a flake-form filler for enhancing reflectance is mixed, followed by burning.

26. (withdrawn) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17, the dielectric layer is formed by attaching to a supporting face a dielectric sheet in which a flake-form filler for enhancing reflectance is dispersed in a state such that the filler is uniformly oriented.

27. (withdrawn) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17, the dielectric layer is formed by attaching and setting to a hollow form a dielectric sheet in which a flake-form filler for enhancing reflectance is dispersed in a state such that the filler is uniformly oriented, and then transferring the dielectric sheet to a substrate.